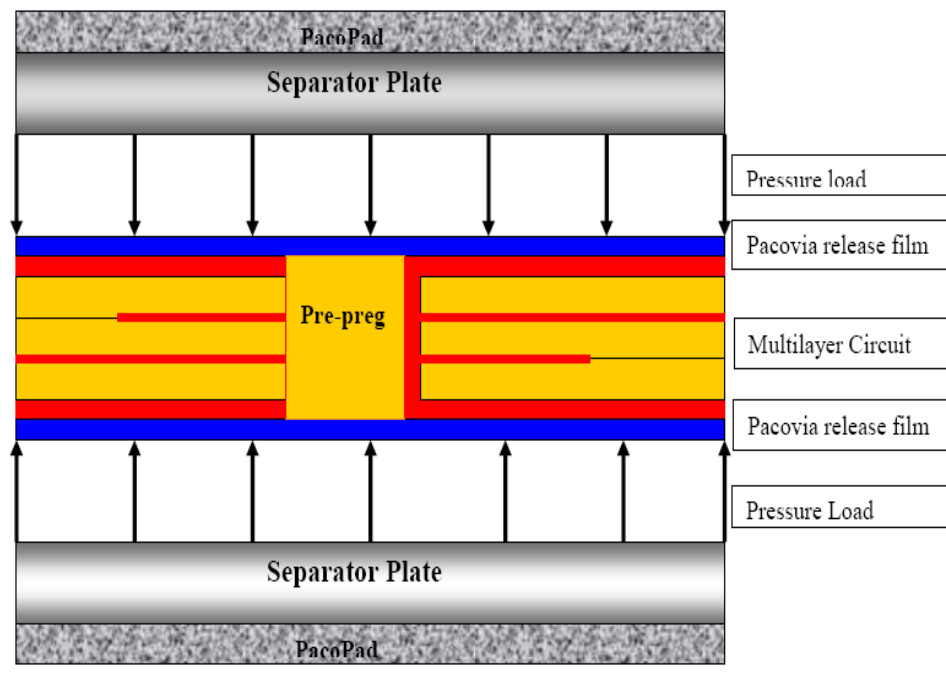


TECHNICAL DATA SHEET

PRODUCT:

PACOVIA 3000 is engineered to provide an easy and reliable technique for laminating Multilayer Printed Circuit Boards that incorporate **buried or blind via hole technology**. PACOVIA placed adjacent to the circuit prevents blind via **resin overflow** which allows discreet control of liquid resin so that internal buried via hole barrels are completely filled.

RECOMMENDED LAMINATION LAY-UP:



TECHNICAL DATA:

Physical Property	Test Method	Reported Units	Typical Values		
Max. Application Temp.	Q 1025	°F/°C	425/218		
Thickness	Q 3019	MiLs	3.25/75μ		
Density	ASTM	G/CM3	0.94		
Heat Shrinkage (Heat, 190 C)	MD TD	Pacothane Method	% %	<5% <5%	
Vicat Softening Temp.	ASTM E794	°C	218		
Appearance	White, Semi-translucent				
Tensile Strength (At yield point)	MD	YP	ASTM D882	kg/cm ²	230
		Elong	ASTM D882	%	410
	TD	YP	ASTM D882	kg/cm ²	190
		Elong	ASTM D882	%	520

SHELF LIFE & STORAGE:

- Material should be kept in dry and clean room, below 113°F (45 °C)
- Shelf life: 12 months from the manufactured date

Note: Pacothane generates this data sheet and specifications that are just for reference. We cannot control the performance impact created from different process, storage and manufacturing variables.